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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









AUIPS6121R

 $5.8m\Omega$ max.

39V tvp.

65A min.

CURRENT SENSE HIGH SIDE SWITCH

Product Summary

Current shutdown

Rds(on)

Vclamp

Features

- Suitable for 12V systems
- Over current shutdown
- Over temperature shutdown
- Current sensing
- Active clamp
- Low current
- Reverse battery
- ESD protection
- Optimized Turn On/Off for EMI

Package



DPak - 5Leads

Applications

- Glow plug
- PTC

Description

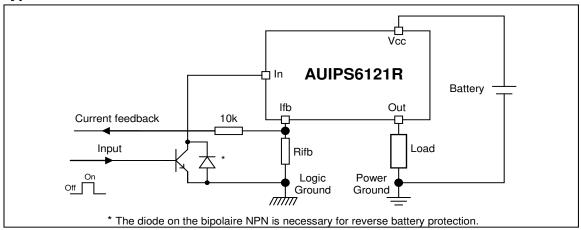
The AUIPS6121R is a fully protected four terminal high side switch. It features current sensing, over-current, over-temperature, ESD protection and drain to source active clamp. Shutdown type of protection provides a good reliability under short circuit condition. The Ifb pin provides both an analog feedback during normal operation and a digital flag when the part is in protection mode.

Ordering Information

Base Part Number		Standard Pack	0 1 5 1 1 1	
base Fait Number	Package Type	Form	Quantity	Complete Part Number
AUIPS6121R	D-Pak-5-Leads	Tube	75	AUIPS6121R
AUIFS0121h	D-Pak-5-Leaus	Tape and reel left	3000	AUIPS6121RTRL



Typical Connection





Absolute Maximum Ratings

Absolute maximum ratings indicate sustained limits beyond which damage to the device may occur. (Tambient=25°C unless otherwise specified).

Symbol	Parameter	Min.	Max.	Units
Vout	Maximum output voltage	Vcc-39	Vcc+0.3	V
Vcc-Vin max.	Maximum Vcc voltage	-18	39	V
lifb, max.	Maximum feedback current	-50	10	mA
Vcc sc	Maximum Vcc voltage with short circuit protection see page 7	_	22	٧
Pd	Maximum power dissipation (internally limited by thermal protection)			W
Fu	Rth=50°C/W Dpack 6cm² footprint	_	2.5	VV
Ti may	Max. operating junction temperature		150	°C
Tj max.	Max. storage junction temperature		150	C

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Units
Rth1	Thermal resistance junction to ambient Dpak Std footprint	70	_	
Rth2	Thermal resistance junction to ambient Dpak 6cm² footprint	50	_	°C/W
Rth3	Thermal resistance junction to case Dpak	1.2	_	

Recommended Operating Conditions These values are given for a quick design.

Symbol	Parameter	Min.	Max.	Units
lout	Continuous output current, Tambient=85°C, Tj=150°C	_	12	Α
	Rth=50°C/W, Dpak 6cm² footprint			
F	Maximum frequency	_	50	Hz



Static Electrical Characteristics

Tj=-40°C..150°C, Vcc=6..18V (unless otherwise specified)

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions	
Vcc op.	Operating voltage range	5.8	_	35	V		
Rds(on)	ON state resistance Tj=25°C	_	4.8	5.8	mΩ	lds=10A	
	ON state resistance Tj=150°C (2)	_	7.5	9	1112.2	IUS=TUA	
Icc off	Supply leakage current	_	1	3		Vin=Vcc=14V,Vifb=Vgnd	
lout off	Output leakage current	_	1	3	μΑ	Vout=Vgnd, Tj=25°C	
lin on	Input current when device on	1	2.7	6	mA	Vcc-Vin=14V	
V clamp	Vcc to Vout clamp voltage	37	39	44			
Vih(1)	High level Input threshold voltage	4.5	5.4	6.2	V	Id=20mA	
Vil(1)	Low level Input threshold voltage	4	5	5.8			
Rds(on) rev	Reverse On state resistance Tj=25°C	_	6	8	mΩ	Isd=10A, Vin-Vcc>8V	
Vf	Forward body diode voltage Tj=25°C	_	0.8	0.9	V	If=10A	
VI	Forward body diode voltage Tj=125°C		0.6	0.8]	II=TUA	
Rin	Input resistor	115	200	300	Ω	Built-in resistor	

- (1) Input thresholds are measured directly between the input pin and the tab.
- (2) Guaranteed by design

Switching Electrical Characteristics

Vcc=14V, Resistive load=1Ω, Tj=25°C

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
Tdon	Turn on delay time	20	50	150		
Tr	Rise time from 20% to 80% of Vcc	15	35	100		See fig. 1
Tdoff	Turn off delay time	20	100	250	μs	See lig. 1
Tf	Fall time from 80% to 20% of Vcc	15	35	100		

Protection Characteristics

Tj=-40°C..150°C, Vcc=6..18V (unless otherwise specified)

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
Tsd	Over temperature threshold(2)	150	165	_	ç	
Isd	Over-current shutdown	65	90	120	Α	See fig. 3
I fault	Ifb after an over-current or an over- temperature (latched)	15	20	27	mA	See lig. 3
OV	Over-voltage protection	18	20	22	V	Vcc-Vin
Psd rst	Time to reset Psd	12	26	60	mo	
Psd_UV	Time to shutdown when Vcc-Out=UV (3)	0.3	0.7	2	ms	

⁽³⁾ See explanation page 8

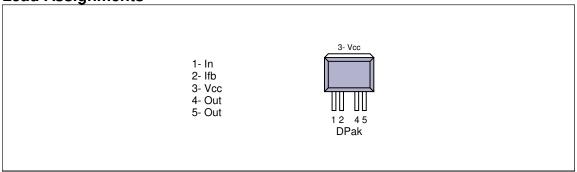
Current Sensing Characteristics

Ti=-40°C..150°C, Vcc=6..18V (unless otherwise specified), Vcc-Vifb>3.5V

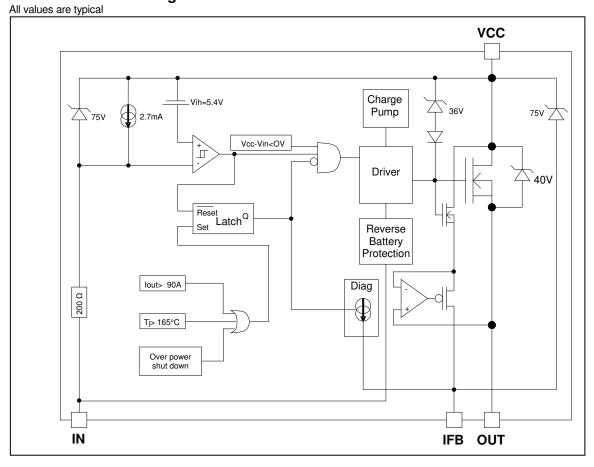
Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
						Iload=60A at Vcc=14V,
Ratio	I load / Ifb current ratio	5000	6300	7600		lload=30A at Vcc=6V,
						after 1.5ms,See page 7
Ratio_Cold	Ratio drift between 25°C to -40°C	-6.6	-2.2	2.1	%	Ratio@-40°/Ratio@25°
Ratio_Hot	Ratio drift between 25°C to 125°C	-1.6	3	7.7	70	Ratio@125°/Ratio@25°
I offset	Load current offset	-0.15	0	0.15	Α	After 1.5ms
Ifb leakage	Ifb leakage current	0	0.5	25	μΑ	Iout=0A, Vcc-Vin=14V



Lead Assignments



Functional Block Diagram





Truth Table

Op. Conditions	Input	Output	Ifb pin voltage
Normal mode	Н	L	0V
Normal mode	L	Н	I load x Rfb / Ratio
Open load	Н	L	0V
Open load	L	Н	Ifb leakage x Rifb
Short circuit to GND	Н	L	0V
Short circuit to GND	L	L	I fault x Rifb(latched)
Over temperature	Н	Ĺ	0V
Over temperature	Ĺ	Ĺ	I fault x Rifb (latched)

Operating voltage

Maximum Vcc voltage: this is the maximum voltage before the breakdown of the IC process.

Operating voltage: This is the Vcc range in which the functionality of the part is guaranteed. The AEC-Q100 qualification is run at the maximum operating voltage specified in the datasheet.

Reverse battery

During the reverse battery the Mosfet is turned on if the input pin is powered with a diode in parallel of the input transistor. Power dissipation in the IPS: P = Rdson rev * I load² + Vcc² / 200ohm (internal input resistor). If the power dissipation is too high in Rifb, a diode in serial can be added to block the current.

Active clamp

The purpose of the active clamp is to limit the voltage across the MOSFET to a value below the body diode break down voltage to reduce the amount of stress on the device during switching.

The temperature increase during active clamp can be estimated as follows:

$$\Delta_{\mathsf{Tj}} = P_{\mathsf{CL}}^{\mathsf{T}} \cdot Z_{\mathsf{TH}}(t_{\mathsf{CLAMP}})$$

Where: $Z_{TL}(t_{CLAMP})$ is the thermal impedance at t_{CLAMP} and can be read from the thermal impedance curves given in the data sheets.

$$P_{CL} = V_{CL} \cdot I_{CLavg}$$
: Power dissipation during active clamp

$$V_{\text{CL}} = 39V$$
 : Typical V_{CLAMP} value

$$I_{CLavg} = \frac{I_{CL}}{2}$$
: Average current during active clamp

$$t_{\text{CL}} = \frac{I_{\text{CL}}}{\left| \frac{di}{dl} \right|} : \text{Active clamp duration}$$

$$\frac{di}{dt} = \frac{V_{Battery} - V_{CL}}{L} : Demagnetization current$$

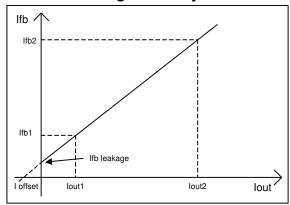
Figure 9 gives the maximum inductance versus the load current in the worst case: the part switches off after an over temperature detection. If the load inductance exceeds the curve, a freewheeling diode is required.

Over-current protection

The threshold of the over-current protection is set in order to guarantee that the device is able to turn on a load with an inrush current lower than the minimum of Isd. Nevertheless for high current and high temperature the device may switch off for a lower current due to the over-temperature protection.



Current sensing accuracy



The current sensing is specified by measuring 3 points :

- Ifb1 for lout1
- Ifb2 for lout2
- Ifb leakage for lout=0

The parameters in the datasheet are computed with the following formula:

Ratio = (lout2 - lout1)/(lfb2 - lfb1)

I offset = Ifb1 x Ratio - Iout1

This allows the designer to evaluate the Ifb for any lout value using:

Ifb = (lout + I offset) / Ratio if Ifb>Ifb leakage

For some applications, a calibration is required. In that case, the accuracy of the system will depends on the variation of the I offset and the ratio over the temperature range. The ratio variation is given by Ratio_Hot and Ratio_Cold specified in page 4.

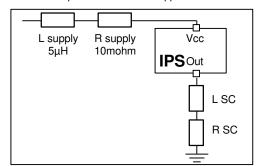
The loffset variation depends directly on the Rdson:

I offset@-40°C= I offset@25°C / 0.8

I offset@150°C= I offset@25°C / 1.9

Maximum Vcc voltage with short circuit protection

The maximum Vcc voltage with short circuit is the maximum voltage for which the part is able to protect itself under test conditions representative of the application. 2 kind of short circuits are considered: terminal and load short circuit.

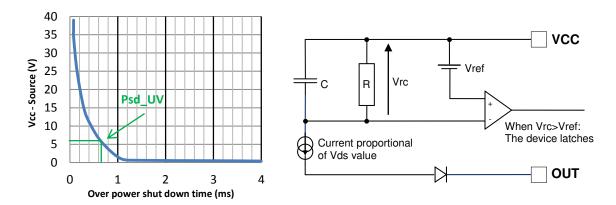


	L SC	R SC
TerminalSC	0.1 μΗ	10 mohm
LoadSC	L supply + L SC = 5 μH	100 mohm



Over power shut down protection

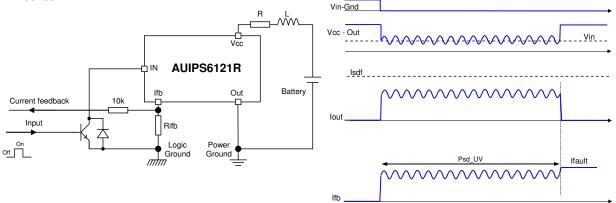
The AUIPS6121R integrates an over-power protection in order to limit the thermal stress in the mosfet during certain conditions like overload or under voltage. The power is measured by monitoring the voltage between Vcc and Source. The device latches more quickly when the power is higher.



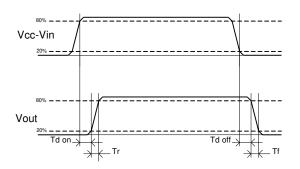
When the device is latched: VRC is discharge with an internal constant (Psd rst).

Typical in low voltage condition with a short circuit on the output, the voltage on the Vcc pin will oscillate around the under voltage protection and the 'over-current shut down' will not be triggered.

The 'Over power shut down' protection will turn off the part after the time 'Psd_UV' for preventing thermal stress of the device.







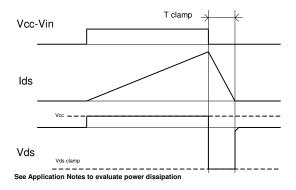


Figure 1 - IN rise time & switching definitions

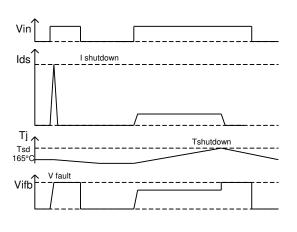


Figure 3 - Protection timing diagram

Figure 2 - Active clamp waveforms

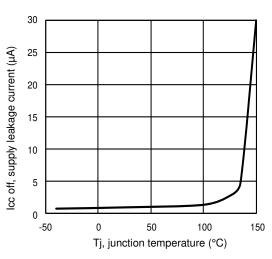


Figure 4 – Icc off (µA) VsTj (°C)

June 23, 2015



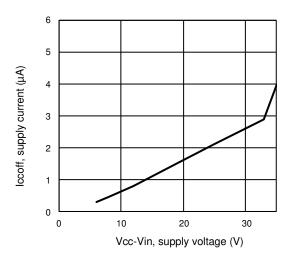


Figure 5 – Icc off (μA) VsVcc-Vin (V)

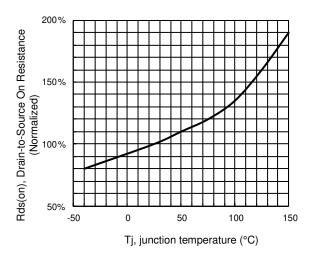


Figure 7 - Normalized Rds(on) (%) Vs Tj (°C)

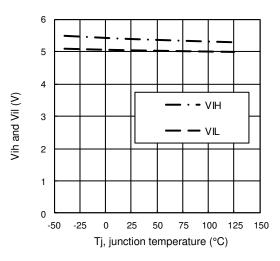


Figure 6 - Vih and Vil (V) VsTj (°C)

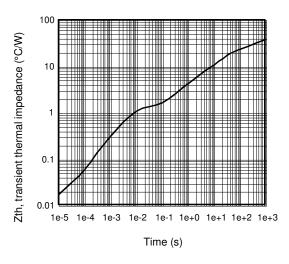


Figure 8 – Transient thermal impedance (°C/W) Vs time (s)



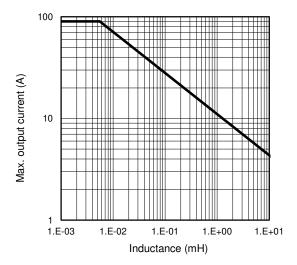


Figure 9 - Max. lout (A) Vs inductance (mH)

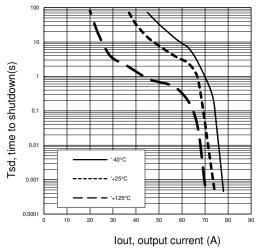
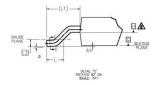
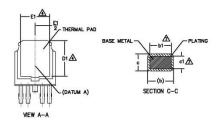


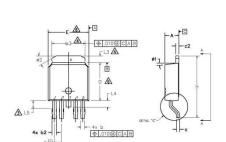
Figure 10 - Tsd (s) Vs I out (A) SMD with 6cm²



Case Outline 5 Lead - DPAK







S	DIMENSIONS					
M B O	MILLIM	ETERS	INC	HES	O	
L	MIN.	MAX.	MIN.	MAX.	Ė	
Α	2.18	2.39	.086	.094		
A1	-	0.13	-	.005		
b	0.56	0.79	.022	.031		
ь1	.056	0.74	.022	.029	2	
b2	0.65	0.89	.026	.035		
b3	4.95	5.46	.195	.215	2	
С	0.46	0.61	.018	.024		
c1	0.41	0.56	.016	.022	2	
c2	0.46	0.89	.018	.035		
D	5.97	6.22	.235	.245	3	
D1	5.21	-	.205	-		
Ε	6.35	6.73	.250	.265	3	
E1	4.32	-	.170	-		
е	1.14	1.14 BSC		BSC		
н	9.40	10.41	.370	.410		
L	1.40	1.78	.055	.070		
L1	2.74	BSC	.108	REF.		
L2	0.51	BSC	.020	BSC		
L3	0.89	1.27	.035	.050		
L4	-	1.02	-	.040		
L5	1.14	1.52	.045	.060		
ø	0.	10*	0.	10°		
ø1	0.	15*	0.	15°		
ø2	28*	32*	28*	32*		

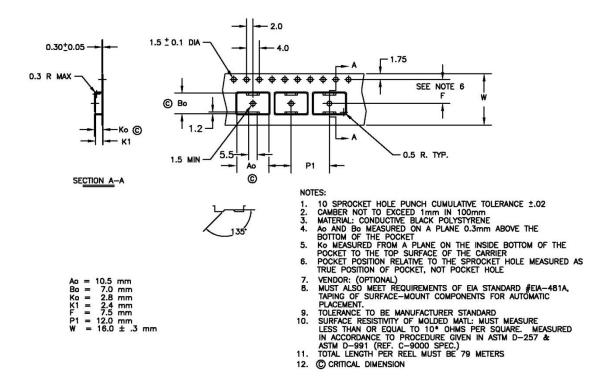
NOTES:

- 1.- DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M-1994
- 2.- DIMENSION ARE SHOWN IN INCHES [MILLIMETERS].
- A- LEAD DIMENSION UNCONTROLLED IN L5.
- A- DIMENSION D1, E1, L3 & b3 ESTABLISH A MINIMUM MOUNTING SURFACE FOR THERMAL PAD.
- 5.- SECTION C-C DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .005 AND 0.10 [0.13 AND 0.25] FROM THE LEAD TIP.
- ⚠ DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005 [0.13] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.
- A- DIMENSION 61 & c1 APPLIED TO BASE METAL ONLY.
- 8.- DATUM A & B TO BE DETERMINED AT DATUM PLANE H.
- 9.- OUTLINE CONFORMS TO JEDEC OUTLINE TO-252.
- 10. LEADS AND DRAIN ARE PLATED WITH 100% Sn

Note: For the most current drawings please refer to the IR website at: http://www.irf.com/package/



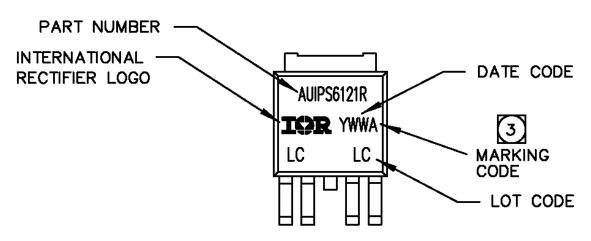
Tape & Reel 5 Lead - DPAK



Note: For the most current drawings please refer to the IR website at: http://www.irf.com/package/



Part Marking Information



Qualification Information[†]

-,						
Qualification Level			Automotive (per AEC-Q100)			
		IR's Industrial and Consumer of	Comments: This family of ICs has passed an Automotive qualification. IR's Industrial and Consumer qualification level is granted by extension of the higher Automotive level.			
Moisture Sensitivity Level		DPAK-5L	MSL2,260°C (per IPC/JEDEC J-STD-020)			
	Machine Model		Class M3 (+/-300V) (per AEC-Q100-003)			
ESD	Human Body Model		ss 2 (+/-3000V) AEC-Q100-002)			
	Charged Device Model		Class C6 (+/-1000V) (per AEC-Q100-011)			
IC Latch-Up Test		(per A	Class II (per AEC-Q100-004)			
RoHS Co	mpliant	Yes				

[†] Qualification standards can be found at International Rectifier's web site http://www.irf.com/



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